

# **BULD118D-1**

# HIGH VOLTAGE FAST-SWITCHING NPN POWER TRANSISTOR

- INTEGRATED ANTIPARALLEL COLLECTOR- EMITTER DIODE
- HIGH VOLTAGE CAPABILITY
- LOW SPREAD OF DYNAMIC PARAMETERS
- MINIMUM LOT-TO-LOT SPREAD FOR RELIABLE OPERATION
- VERY HIGH SWITCHING SPEED

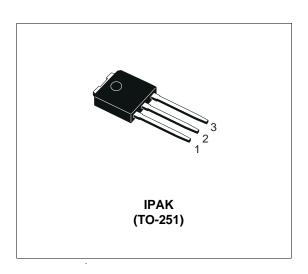
#### **APPLICATIONS:**

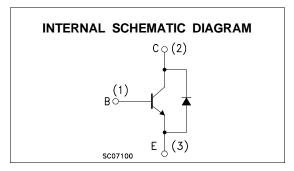
- ELECTRONIC BALLASTS FOR FLUORESCENT LIGHTING
- FLYBACK AND FORWARD SINGLE TRANSISTOR LOW POWER CONVERTERS

#### **DESCRIPTION**

The device is manufactured using high voltage Multi Epitaxial Planar technology for high switching speeds and medium voltage capability. It uses a Cellular Emitter structure with planar edge termination to enhance switching speeds while maintaining the wide RBSOA.

The device is designed for use in lighting applications and low cost switch-mode power supplies.





#### ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V <sub>CES</sub>	Collector-Emitter Voltage (V <sub>BE</sub> = 0)	700	V
V <sub>CEO</sub>	Collector-Emitter Voltage (I <sub>B</sub> = 0)	400	V
V <sub>EBO</sub>	Emitter-Base Voltage (I <sub>C</sub> = 0)	9	V
Ic	Collector Current	2	Α
I <sub>CM</sub>	Collector Peak Current (t <sub>p</sub> < 5 ms)	4	А
lΒ	Base Current	1	Α
I <sub>BM</sub>	Base Peak Current (t <sub>p</sub> < 5 ms)	2	Α
$P_{tot}$	Total Dissipation at T <sub>c</sub> = 25 °C	20	W
T <sub>stg</sub>	Storage Temperature	-65 to 150	°C
Ti	Max. Operating Junction Temperature	150	°C

June 2001 1/7

#### THERMAL DATA

R <sub>thj-case</sub>	Thermal Resistance Junction-Case	Max	6.25	°C/W	
R <sub>thj-amb</sub>	Thermal Resistance Junction-Ambient	Max	100	°C/W	

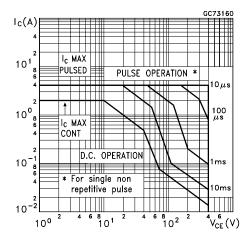
# **ELECTRICAL CHARACTERISTICS** (T<sub>case</sub> = 25 °C unless otherwise specified)

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Unit
I <sub>CES</sub>	Collector Cut-off Current (V <sub>BE</sub> = 0)	V <sub>CE</sub> = 700 V V <sub>CE</sub> = 700 V	T <sub>j</sub> = 125 °C			100 500	μA μA
$V_{EBO}$	Emitter-Base Voltage	I <sub>E</sub> = 10 mA		9			V
V <sub>CEO(sus)</sub>	Collector-Emitter Sustaining Voltage	I <sub>C</sub> = 100 mA	L = 25 mH	400			V
I <sub>CEO</sub>	Collector-Emitter Leakage Current	V <sub>CE</sub> = 400 V				250	μΑ
V <sub>CE(sat)</sub> *	Collector-Emitter Saturation Voltage	I <sub>C</sub> = 0.5 A I <sub>C</sub> = 1 A I <sub>C</sub> = 2 A	$I_B = 0.1 A$ $I_B = 0.2 A$ $I_B = 0.4 A$			0.5 1 1.5	V V V
V <sub>BE(sat)*</sub>	Base-Emitter Saturation Voltage	I <sub>C</sub> = 0.5 A I <sub>C</sub> = 1 A I <sub>C</sub> = 2 A	I <sub>B</sub> = 0.1 A I <sub>B</sub> = 0.2 A I <sub>B</sub> = 0.4 A			1.0 1.2 1.3	V V V
h <sub>FE</sub> *	DC Current Gain	I <sub>C</sub> = 10 mA I <sub>C</sub> = 0.5 A I <sub>C</sub> = 2 A	V <sub>CE</sub> = 5 V V <sub>CE</sub> = 5 V V <sub>CE</sub> = 5 V	10 10 8		50	
t <sub>r</sub> t <sub>f</sub> t <sub>s</sub>	RESISTIVE LOAD Rise Time Fall Time Storage Time group A group B	$V_{CC} = 125 \text{ V}$ $I_{B1} = 0.4 \text{ A}$ $t_p = 30  \mu\text{s}$	I <sub>C</sub> = 2 A I <sub>B2</sub> = -0.2 A	1.4	0.7 0.3	0.5 2.1 2.75	μs μs μs μs
t <sub>s</sub> t <sub>f</sub>	INDUCTIVE LOAD Storage Time Fall Time	Ic = 1 A V <sub>BE</sub> = -5 V V <sub>clamp</sub> = 300 V	I <sub>B1</sub> = 0.2 A L = 50 mH		0.8 0.10		μs μs
$V_{F}$	Diode Forward Voltage	$I_C = 1 A$				2.5	V

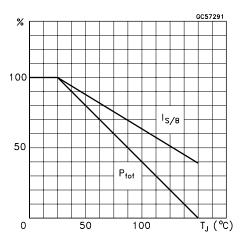
Pulsed: Pulse duration = 300 µs, duty cycle 1.5 %

Note: Product is pre-selected in storage time (GROUP A and GROUP B). STMicroelectronics reserves the right to ship either groups according to production availability. Please contact your nearest STMicroelectronics sales office for delivery details.

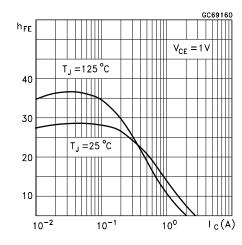
# Safe Operating Areas



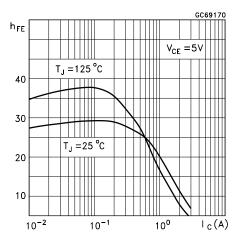
### **Derating Curve**



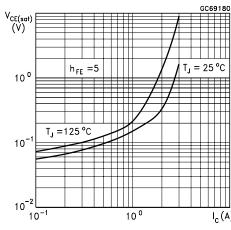
DC Current Gain



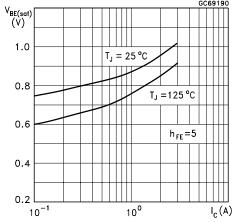
DC Current Gain



Collector Emitter Saturation Voltage

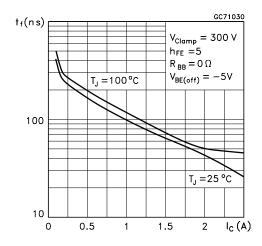


Base Emitter Saturation Voltage

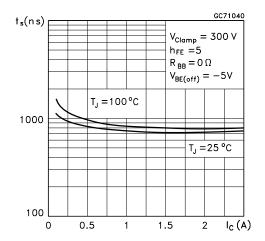


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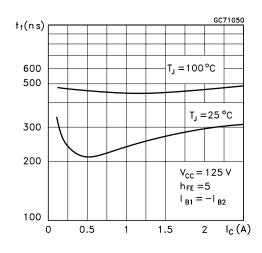
### Inductive Fall Time



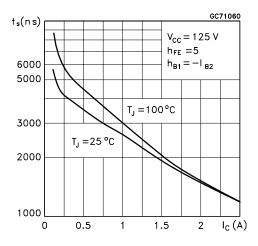
# Inductive Storage Time



#### Resistive Fall Time



Resistive Load Storage Time



## Reverse Biased SOA

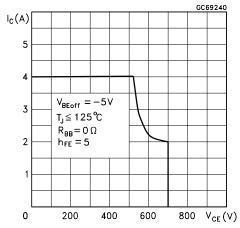


Figure 1: Inductive Load Switching Test Circuit.

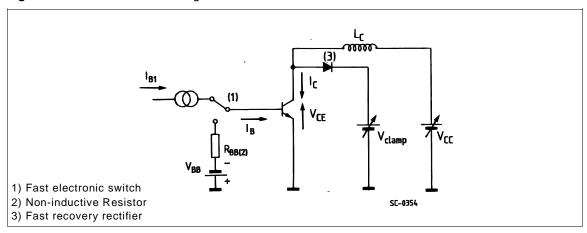
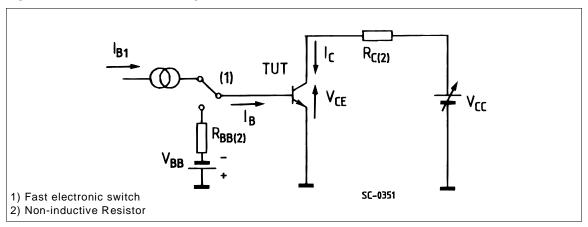
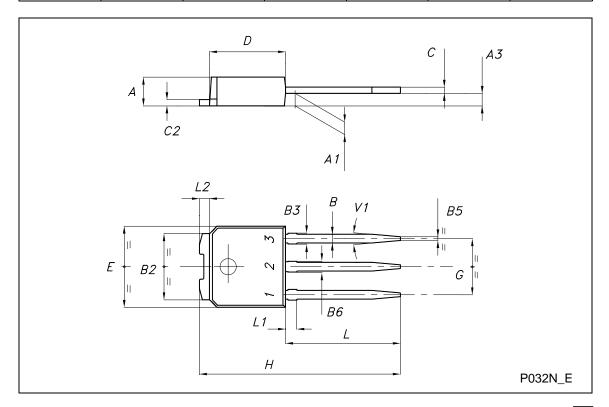


Figure 2: Resistive Load Switching Test Circuit.



# **TO-251 (IPAK) MECHANICAL DATA**

DIM.	mm			inch			
DINI.	MIN.	TYP.	MAX.	MIN.	TYP.	MAX.	
А	2.20		2.40	0.087		0.094	
A1	0.90		1.10	0.035		0.043	
А3	0.70		1.30	0.028		0.051	
В	0.64		0.90	0.025		0.035	
B2	5.20		5.40	0.204		0.213	
В3			0.85			0.033	
B5		0.30			0.012		
В6			0.95			0.037	
С	0.45		0.60	0.018		0.024	
C2	0.48		0.60	0.019		0.024	
D	6.00		6.20	0.237		0.244	
Е	6.40		6.60	0.252		0.260	
G	4.40		4.60	0.173		0.181	
Н	15.90		16.30	0.626		0.642	
L	9.00		9.40	0.354		0.370	
L1	0.80		1.20	0.031		0.047	
L2		0.80	1.00		0.031	0.039	
V1		10°			10°		



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